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#2827



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 09/848,932 Confirmation No.: 7101
First Named Inventor: Hoffman, Paul Filing Date: May 4, 2001
Group Art Unit: 2827 Examiner: Cruz, Lourdes C.
Atty. Docket No.: M-9954 US
Title: Shielded Semiconductor Package With Single-Sided Substrate And Method For Making The Same
Assignee: Amkor Technology, Inc.

San Francisco, California
January 13, 2003

BOX NON-FEE AMENDMENT
COMMISSIONER FOR PATENTS
Washington, D. C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

This paper is in response to the non-final Office Action dated October 11, 2002.
Applicants respectfully request reconsideration of the application in view of the following.

IN THE CLAIMS

The following is a clean version of the set of pending claims. In accordance with 37 C.F.R. §1.121(c)(1)(ii), Attachment A provides marked up version of the claims containing the newly introduced changes.

11. A semiconductor chip package comprising:
- a substrate;
 - a metallization layer formed on one side of the substrate;

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